PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6770116

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIANYU SONG	06/07/2021

RECEIVING PARTY DATA

Name:	SZ DJI TECHNOLOGY CO., LTD.	
Street Address:	NO. 18 GAOXIN SOUTH 4TH AVENUE, NANSHAN DISTRICT	
Internal Address:	17/F WEST WING, SKYWORTH SEMICONDUCTOR DESIGN BLDG	
City:	SHENZHEN	
State/Country:	CHINA	
Postal Code:	518057	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15816455

CORRESPONDENCE DATA

Fax Number: (703)935-1394

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

7034305759 Phone:

Email: uspto@anovalaw.com

Correspondent Name: ANOVA LAW GROUP, PLLC

Address Line 1: 21495 RIDGETOP CIRCLE, SUITE 300

Address Line 4: STERLING, VIRGINIA 20166

ATTORNEY DOCKET NUMBER:	00203.1237.00US
NAME OF SUBMITTER:	HOI CHEUNG
SIGNATURE:	/Hoi Cheung/
DATE SIGNED:	06/18/2021

Total Attachments: 2

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> **PATENT** REEL: 056586 FRAME: 0170

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

CONTROL METHODS AND APPARATUSES BASED ON HEADLESS MODE FOR UNMANNED AERIAL VEHICLE

for which I/We executed an application for United States Letters Patent herewith, as a national application in the United States of PCT Application No. ______, or filed an application for United States Letters Patent on November 17, 2017 (Application No. 15/816,455); and

WHEREAS, <u>SZ DJI TECHNOLOGY CO., LTD.</u>, a limited company of <u>P.R.China</u>, whose post office address is <u>17/F West Wing</u>, <u>Skyworth Semiconductor Design Bldg.</u>, <u>No. 18 Gaoxin South 4th Avenue</u>, <u>Nanshan District</u>, <u>Shenzhen</u>, <u>Guangdong</u>, <u>518057</u>, <u>P.R. China</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in United States, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1:

Name:

Jianyu SONG

Address:

17/F West Wing, Skyworth Semiconductor Design Bldg., No. 18 Gaoxin South 4th Avenue, Nanshan District, Shenzhen, Guangdong 518057 P.R. China

Signature:

Date:

2021-06-07